DISCRETE SEMICONDUCTORS



Preliminary specification File under Discrete Semiconductors, SC01 1996 Jun 05



FEATURES

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Guaranteed avalanche energy absorption capability
- UL 94V-O classified plastic package
- Shipped in 12 mm embossed tape.

DESCRIPTION

DO-214AC surface mountable package with glass passivated chip.

The well-defined void-free case is of a transfer-moulded thermo-setting plastic.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage				
	BYG70D		_	200	V
	BYG70G		_	400	V
	BYG70J		_	600	V
V _R	continuous reverse voltage				
	BYG70D		-	200	V
	BYG70G		_	400	V
	BYG70J		_	600	V
I _{F(AV)}	average forward current	averaged over any 20 ms period; T _{tp} = 100 °C; see Fig.2	_	1.00	A
		averaged over any 20 ms period; Al ₂ O ₃ PCB mounting (see Fig.7); $T_{amb} = 60 \degree$ C; see Fig.3	_	0.53	A
		averaged over any 20 ms period; epoxy PCB mounting (see Fig.7); T _{amb} = 60 °C; see Fig.3	_	0.39	A
I _{FSM}	non-repetitive peak forward current	t = 10 ms half sine wave; T _j = T _{j max} prior to surge; $V_R = V_{RRMmax}$	_	20	A
E _{RSM}	non-repetitive peak reverse avalanche energy	L = 120 mH; $T_j = T_{j max}$ prior to surge; inductive load switched off	-	10	mJ
T _{stg}	storage temperature		-65	+175	°C
Tj	junction temperature	see Fig.4	-65	+175	°C

BYG70 series

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ELECTRICAL CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _F	forward voltage	$I_F = 1 \text{ A}; T_j = T_{j \text{ max}}$ see Fig.5	_	_	2.1	V
		I _F = 1 A; see Fig.5	-	_	3.6	V
V _{(BR)R}	reverse avalanche breakdown voltage	I _R = 0.1 mA				
	BYG70D		300	_	-	V
	BYG70G		500	_	_	V
	BYG70J		700	_	-	V
I _R	reverse current	V _R = V _{RRMmax} ; see Fig.6	-	_	5	μA
		V _R = V _{RRMmax} ; T _j = 165 °C; see Fig.6	-	_	100	μA
t _{rr}	reverse recovery time	when switched from $I_F = 0.5$ A to $I_R = 1$ A; measured at $I_R = 0.25$ A; see Fig.8	-	-	30	ns
C _d	diode capacitance	V _R = 0 V; f = 1 MHz	_	30	_	pF

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point		25	K/W
R _{th j-a}	thermal resistance from junction to ambient	note 1	100	K/W
		note 2	150	K/W

Notes

- 1. Device mounted on Al₂O₃ printed-circuit board, 0.7 mm thick; thickness of copper \ge 35 µm, see Fig.7.
- 2. Device mounted on epoxy-glass printed-circuit board, 1.5 mm thick; thickness of copper ≥40 μm, see Fig.7. For more information please refer to the *'General Part of Handbook SC01'*.

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Preliminary specification

GRAPHICAL DATA



Fig.2 Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).





$$\label{eq:VR} \begin{split} V_R = V_{RRMmax}; \, \delta = 0.5; \, a = 1.57. \\ \text{Device mounted as shown in Fig.7}; \\ \text{solid line: Al}_2O_3 \text{ PCB}; \, \text{dotted line: epoxy PCB}. \end{split}$$

Fig.3 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).



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Input impedance oscilloscope: 1 MΩ, 22 pF; $t_r \le 7$ ns. Source impedance: 50 Ω; $t_r \le 15$ ns.



PACKAGE OUTLINE



DEFINITIONS

Data sheet status		
Objective specification	This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		
more of the limiting values of the device at these or at	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or may cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification limiting values for extended periods may affect device reliability.	
Application information		
Where application informat	ion is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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